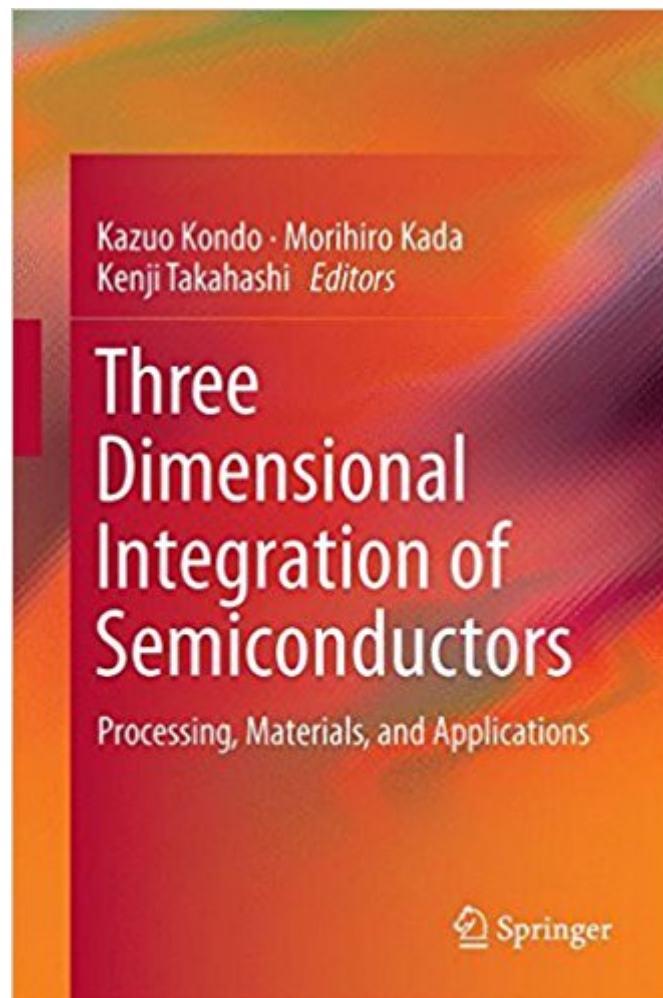




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Three-Dimensional Integration Of Semiconductors: Processing, Materials, And Applications



Synopsis

This book starts with background concerning three-dimensional integration - including their low energy consumption and high speed image processing - and then proceeds to how to construct them and which materials to use in particular situations. The book covers numerous applications, including next generation smart phones, driving assistance systems, capsule endoscopes, homing missiles, and many others. The book concludes with recent progress and developments in three dimensional packaging, as well as future prospects.

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